

Features

Collector Current: I_C=0.6A

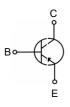
Power Dissipation of 250mW

C Harden

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBT2907ALT1G	SOT-23	2F	3000





Maximum Ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	-60	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V_{EBO}	-5	V
Collector Current	I _C	-600	mA
Collector Power Dissipation	P _C	250	mW
Thermal Resistance From Junction To Ambient	R _{⊝JA}	500	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T_{stg}	- 55∼+150	°C

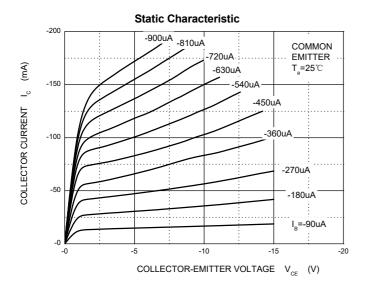


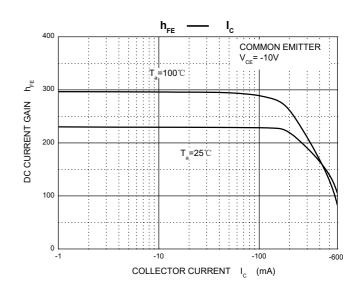
Electrical Characteristics (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	I_{C} =-10 μ A, I_{E} =0	-60			V
Collector-emitter breakdown voltage	$V_{(BR)CEO^*}$	I _C =-10mA,I _B =0	-40			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I _E =-10μA,I _C =0	-5			V
Collector cut-off current	I _{CBO}	V_{CB} =-50V, I_{E} =0			-20	nA
Base cut-off current	I _{EBO}	V _{EB} =-3V, I _C =0			-10	nA
Collector cut-off current	I _{CEX}	V _{CE} =-30 V, V _{BE(off)} =-0.5V			-50	nA
	h _{FE(1)*}	V _{CE} =-10V,I _C =-150mA	100		300	
DC current gain	h _{FE(2)*}	V _{CE} =-10V,I _C =-0.1mA	52			
	h _{FE(3)} *	V _{CE} =-10V,I _C =-500mA	32			
Collector emitter acturation voltage	V _{CE(sat)*}	I _C =-150mA,I _B =-15mA			-0.4	V
Collector-emitter saturation voltage	V _{CE(sat)*}	I _C =-500mA,I _B =-50mA			-0.67	V
Raco emitter caturation voltage	V _{BE(sat)*}	I _C =-150mA,I _B =-15mA			-1	V
Base-emitter saturation voltage	V _{BE(sat)*}	I _C =-500mA,I _B =-50mA			-1.2	٧
Transition frequency	f _T	V _{CE} =-20V,I _C =-50mA,f=100MHz	200			MHz
Delay time	t _d				10	ns
Rise time	t _r	V_{CE} =-30V, I_{C} =-150mA, B_{1} =-15mA			25	ns
Storage time	ts	V _{CE} =-6V,I _C =-150mA,			225	ns
Fall time	t _f	I _{B1} =- I _{B2} =- 15mA			60	ns

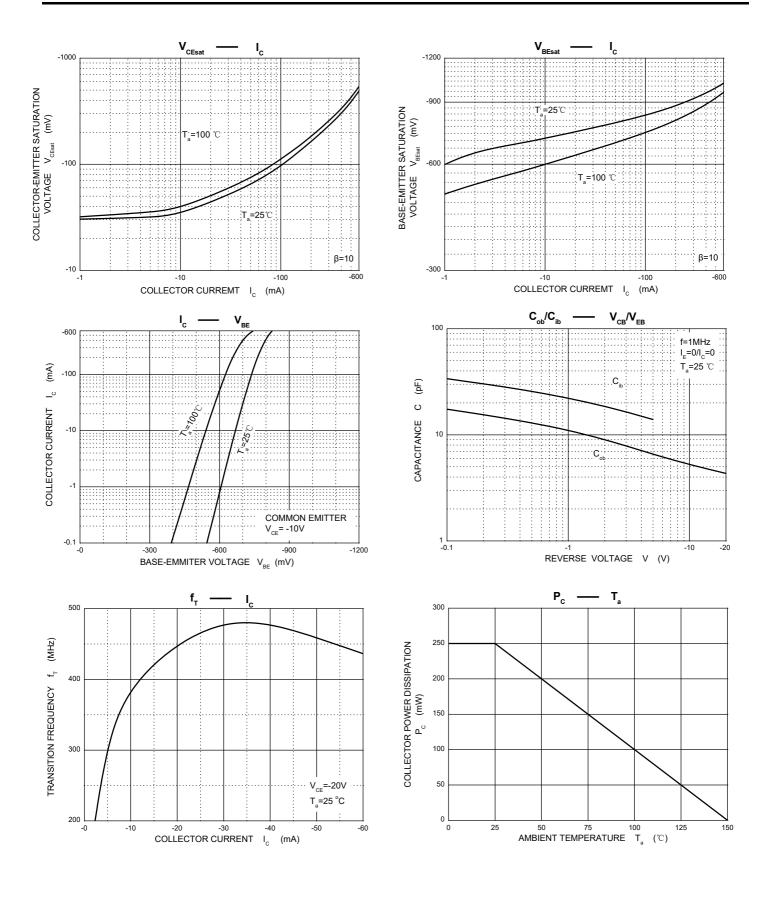
^{*}Pulse test: t_p≤300μs, δ≤0.02.

Typical Characteristics



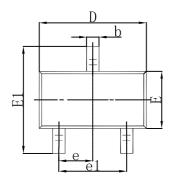


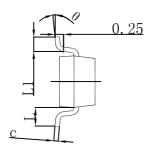


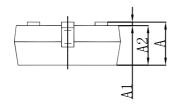




SOT-23 Package Outline Dimensions

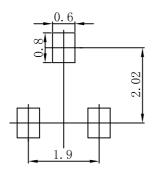






Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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